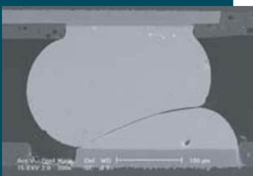
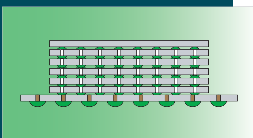
BGA/CSP Development Update Service

Fourth Quarter, 2004





The fourth quarterly BGA/CSP update for 2004 features special coverage of the market with a forecast for BGAs and CSPs in units. Growth in the market is analyzed based on input from captive and merchant assembly operations. Market projections for BGA unit shipments are provided for PBGAs, TBGAs, and ceramic packages. CSP market projections are broken out into laminate substrates, ceramic substrates, leadframe-based packages, and stacked die packages. Key applications and drivers for unit volume and revenue growth are highlighted. A special section is devoted to high performance device packaging trends and memory packaging developments. Packaging trends for high performance logic and memory are highlighted with a special focus on ASICs, DRAM, and flash memory. High performance packaging trends include maximum body size, pin count, and ball pitch. The use of green materials and specific problems encountered with Pb-free packages are discussed.

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